

Appl. No.10/565,044; Docket No. US03 0251 US2
Amdt. dated November 30, 2006
Response to Office Action dated October 31, 2006

Amendments to the Claims

1. (CANCELLED)

Claims 2-11 (CANCELLED)

12. (CANCELLED)

13. (CURRENTLY AMENDED) A method for controlling impedance of bond wires in packaging a semiconductor device die in a package, the method comprising: defining locations of signal and power/ground pads on the device die; defining grounding trace locations on the package; bonding the signal pads and power/ground pads of the device die; providing a conductive path including a ground arch over the bond wires and grounding trace locations, rotating the package a predetermined amount and providing an additional ground arch; and encapsulating the device die and the ground arch and additional ground arch.
~~and encapsulating the device die and ground arch, and rotating the package a pre-determined amount; and providing an additional ground arch.~~

14. (CURRENTLY AMENDED) The method of claim 13 wherein the pre-determined rotation amount amount is about 90°. is about 90 degrees.

15. (ORIGINAL) The method of claim 13, wherein providing an additional ground arch is a function of device design, package size, number of wire bonds, and a desired impedance.

16. (ORIGINAL) The method of claim 15, wherein the desired impedance is function of a ground arch distance from a wire bond.